## **Tyrone Camarero Specifications**



Camerero: SSI200A2W-110

**Kev Feature** 

1U UP CloudDC with 10 hot-swap 2.5" NVMe/SAS/SATA bays and 2 PCIe 5.0 slots + 2 PCIe 5.0 AIOM slots

Virtualization, HPC, CDN, Edge Nodes, Cloud Computing, Data Center Optimized, Storage Headnode

- Single Socket E (LGA-4677) 4th Gen Intel® Xeon® Scalable processors. Up to 350W TDP
- Intel® C741 Chipset
- 16 DIMMs; Supports 3DS DDR5 RDIMM. Up to 5600 MHz
- 2 PCle 5.0 x16 FHHL slot(s), 2 PCle 5.0 x16 AIOM slot(s) (OCP 3.0 compatible)
- Dual AIOM (OCP 3.0) for networking (NCSI available), 1 dedicated IPMI LAN
- 10x front hot-swap 2.5" SATA3 drive bays (Optional all 10 hybrid Gen5 NVMe), SAS3 with additional SAS controller card
- Fans 6 middle cooling PWM 40x40x56mm Fan(s)
- 2x 800W/860W Redundant (1 + 1) Titanium Level power supplies





Processor/	'Cache
Processor/	Cacne

Single Socket E (LGA 4677) 4th Gen Intel® Processor

Xeon® Scalable processors. Up to 60C/120T;

Up to 112.5MB Cache.

Note: Supports up to 350W TDP CPUs (Aircooled) CPUs (air cooled) with TDP over 300W are only supported under specific

conditions.

Chipset

Chipset Intel® C741 Chipset

**System Memory** 

Memory 16 DIMM slots, Up to 4TB: 16x 256

GB DRAM, Memory Type: Capacity

4800/4400MHz ECC DDR5

**RDIMM** 

**Expansion Slot** 

2 PCle 5.0 x16 FHHL slot(s), 2 PCle 5.0 x16 **PCI-Express** 

AIOM slot(s) (OCP 3.0 compatible)

**Integrated Onboard:** 

SATA (6Gbps); RAID 0/1/5/10 support SATA

1 RJ45 Dedicated IPMI LAN port LAN

Add-on Options

**Raid Card** Optional

Optical None

Drive

## Front Panel

LED Device Activity, LAN 1 Activity, LAN 2

Activity, Power status System

information.

**Buttons** Power On/Off UID button

Drive bays

**HDD Bays** 10x 2.5" NVMe/SATA/SAS drive bays

(10x 2.5" NVMe hybrid) 2x PCle 3.0 x 2

M-key, 2280, 22110

**Power Supply** 

2x 800W/860W Redundant (1 + 1) **Power Supply** 

Titanium Level power supplies

Cooling System

6 middle cooling PWM 40x40x56mm Fans

Fan(s)

Form Factor

Form Factor 1U Rackmount

Dimensions

**Dimensions** Height 1.7" (43mm), Width 17.2"

(437mm), Depth 23.5" (597mm)

Email: Info@tyronesystems.com For more/current product information, Visit www.tyronesystems.com

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